

# Taiwan Advanced Packaging Hub

**APEX  
EXPO  
2026**  
by Global Electronics Association

**Booths No.**

**3842、3843、3844、3942、3944、3945**

2026.3.17-19 @ Anaheim Convention Center (HALL C)

# Taiwan Advanced Packaging Hub

<p><b>Taiwan Printed Circuit Association (TPCA)</b></p> <p><b>3844</b></p>	<p><b>Tai Hong Circuit Industrial Co., Ltd.</b></p> <p><b>3945</b></p>
<p><b>Vesta Microsystem Co., Ltd.</b></p> <p><b>3843</b></p>	<p><b>Gredmann Taiwan Ltd.</b></p> <p><b>3944</b></p>
<p><b>Kaston Co., Ltd.</b></p> <p><b>3842</b></p>	<p><b>Microcosm Technology Co., Ltd.</b></p> <p><b>3942</b></p>



## Overview

Taiwan plays a critical role in the global AI-server ecosystem through its semiconductor and PCB sectors.

Industry statistics show that Taiwanese-invested PCB production ranks among the world's leading producers, while Taiwan holds dominant global market shares of 69% in semiconductors, 51% in assembly and testing services, and 35% in IC substrates. As AI applications and heterogeneous integration continue to accelerate, these market shares are expected to expand further, reinforcing the strategic importance of Taiwan's PCB and semiconductor industries.

At APEX EXPO 2026, the Taiwan Printed Circuit Association (TPCA), together with member companies, presents the **Taiwan Advanced Packaging Hub**, showcasing representative technologies and industrial strengths in advanced packaging and high-end PCBs, while promoting collaboration and engagement with international partners.

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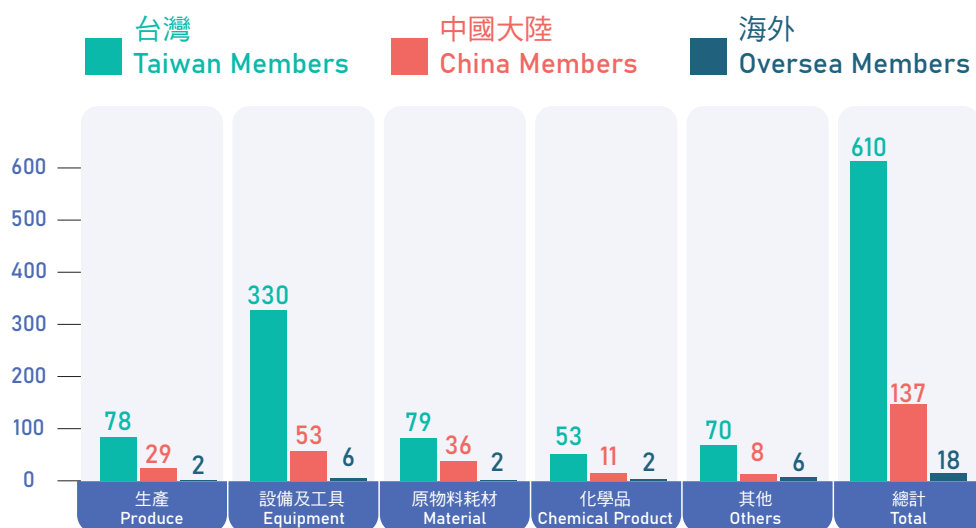
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# The Introduction of TPCA

TPCA成立於1998年，位於桃園高鐵和機場附近，是台灣PCB產業的樞紐。台灣的PCB產業擁有超過760家會員，產值位居全球領先地位。TPCA致力於提供多元專業服務、促進多管道合作、參與國際事務、推廣環境公益事務、出版產業報告，並透過會員協作推動永續發展及強化風險治理的韌性。

TPCA, established in 1998 and situated near the Taoyuan HSRS and Airport, is the hub of the PCB industry in Taiwan. With over 760 members, Taiwan's PCB industry is the global leader in production value. TPCA is dedicated to providing diverse range professional services, fostering collaboration through various channels, participating in international affairs, Promote environmental public welfare affairs, publishing industry reports, and advancing sustainable development while strengthening resilience in risk management through member collaboration.

## Members of TPCA



### TPCA 願景

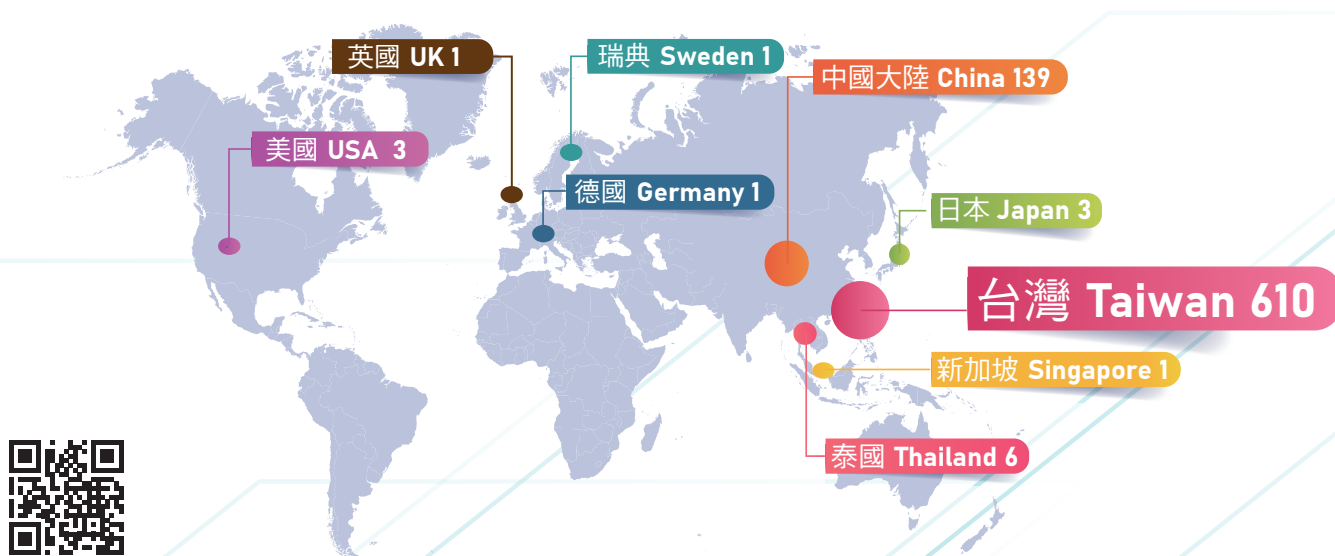
「凝聚會員，提升產業競爭力，共創永續新價值。」

The vision of TPCA is "gathering members, improving the competitiveness of the industry, and creating sustainable new value".

## Total 765

Updated Date : 2025.Nov

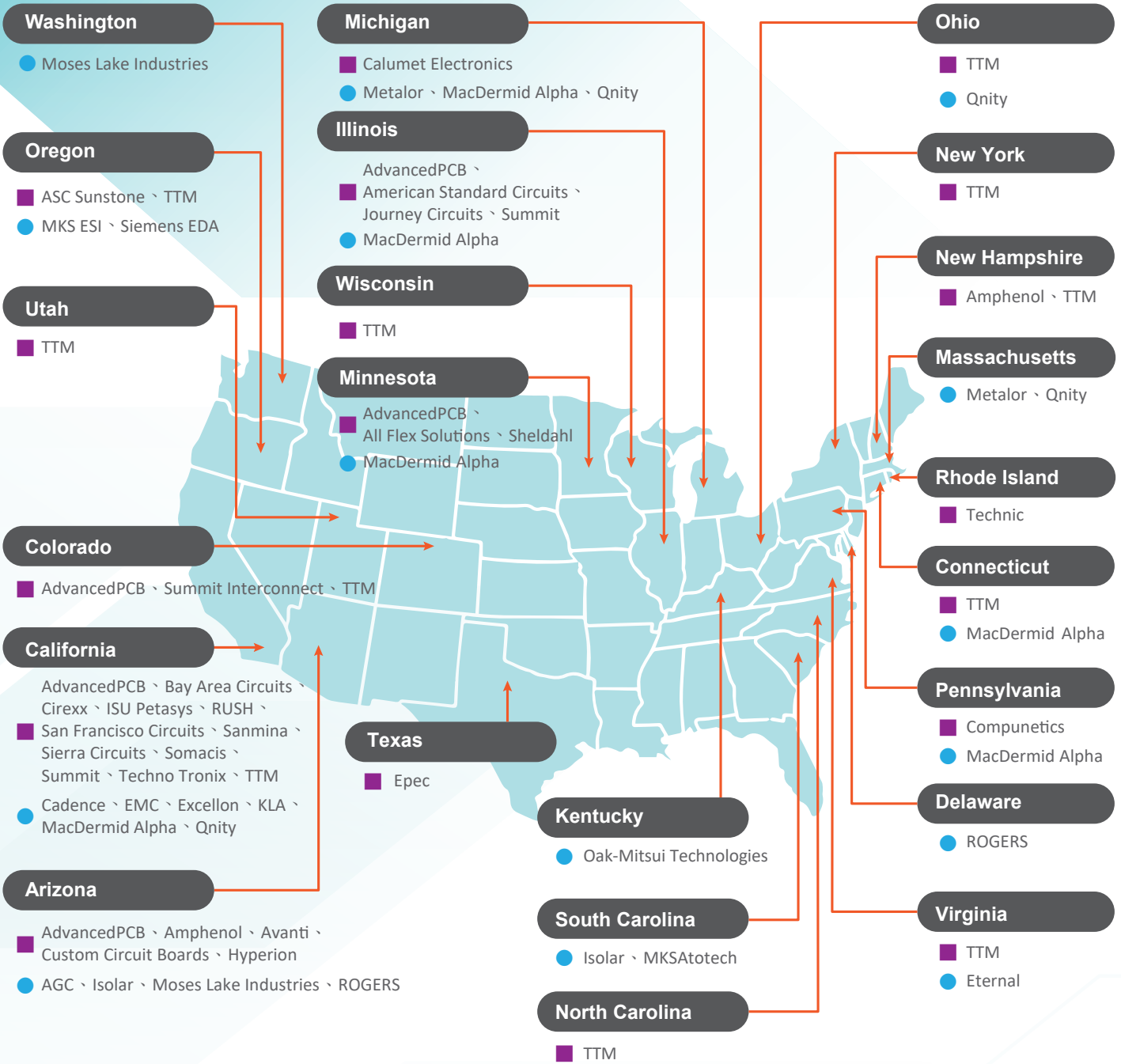
## Members Distribution



TPCA Web

# PCB Industry in the USA \*1

■ PCB Maker ● PCB Supply Chain\*2



**Note:**

1. Arranged in alphabetical order. The map focuses on actual manufacturing and production sites and does not include office locations.
2. Including material, chemical, equipment, and software.

Source: TPCA (2025/12)

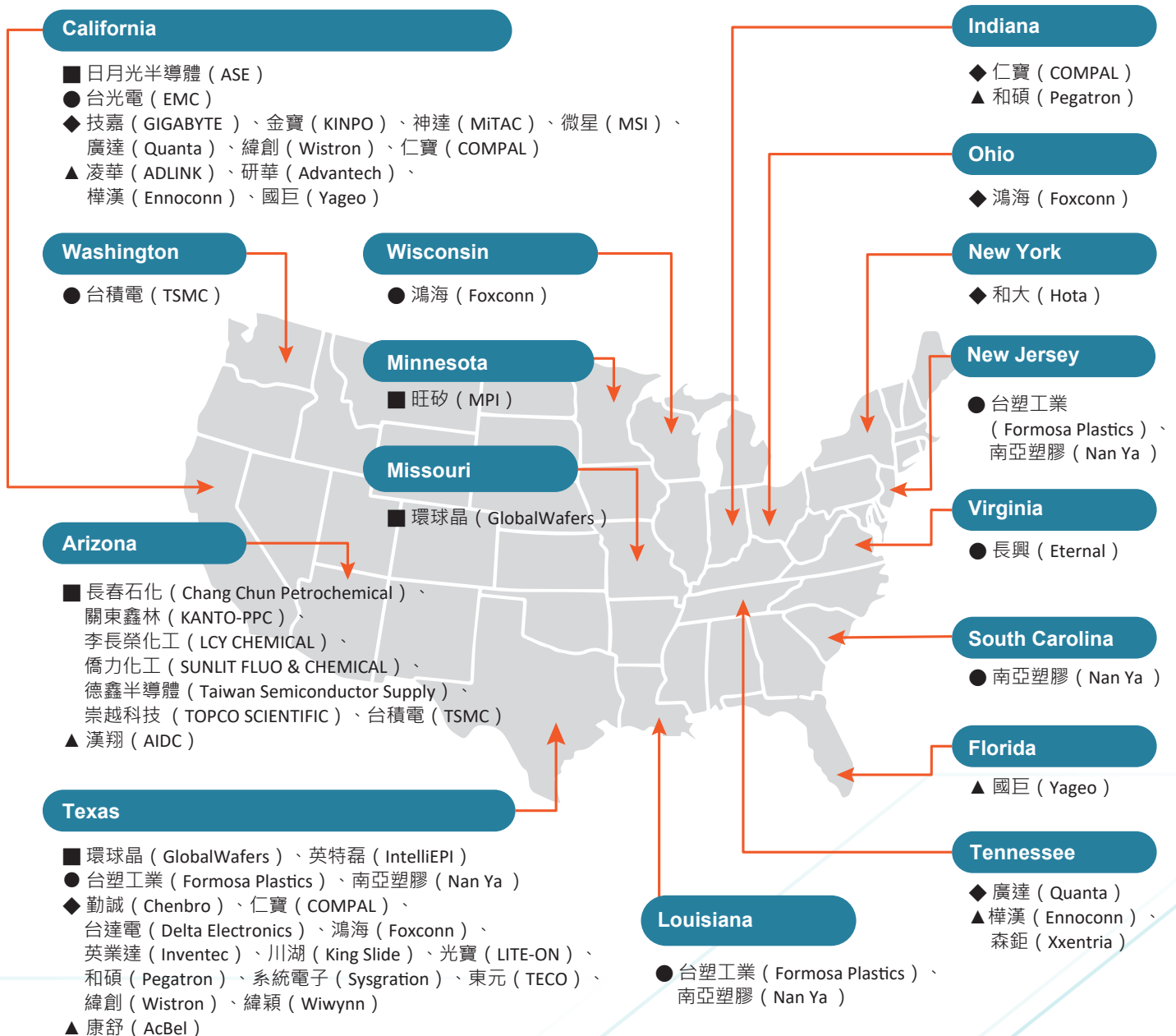
# Taiwan Manufacturing in the USA\*1

■ Semiconductor-Related\*2

◆ Automotive and Server-Related\*3

● Chemical and Material-Related

▲ Others



Note:

1. Arranged in alphabetical order. The map focuses on actual manufacturing and production sites and does not include office locations.
2. Including manufacturing, material, chemical, equipment, facility.
3. Including EMS, component and module.

Source: TPCA (2025/12)

Booth No. 3842

**Kaston Co., Ltd.**  
 AJ Co., Ltd. (Located in Japan)  
**嘉世通企業有限公司**



<b>Company Address</b>	Rm1, 12F., No.6, Sec.2, Daxing W. Rd., Taoyuan Dist., Taoyuan City 330, Taiwan (R.O.C)
<b>Website</b>	<a href="https://kaston.com.tw">https://kaston.com.tw</a>
<b>Registered Capital</b>	10,000,000 NTD
<b>Total Number of Employees</b>	15 members
<b>Main Products</b>	Electronic materials/Machine parts/Processing products/ Grinding & Polishing skills

### Company Introduction

AJ & KASTON specialize in the PCB and semiconductor manufacturing industries, providing integrated solutions covering process equipment, critical components, and high-performance materials to enhance process stability, yield, and mass-production reliability.

Our core technologies focus on high-temperature capability, non-silicone, low-VOC, and low-contamination processes.

By integrating vacuum lamination systems, heating solutions, and process fixtures, together with heat-resistant films, functional tapes, protective materials, and advanced surface treatment technologies,

we support a wide range of applications including ABF substrates, HDI, exposure, lamination, baking, and advanced packaging processes.

Beyond product supply, AJ & KASTON leverage deep on-site process knowledge to provide process optimization proposals, including equipment parameter tuning, material selection, and process condition improvement.

These solutions effectively reduce particle contamination, process defects, delamination, and thermal deformation risks, enabling higher yields and long-term stable mass production.

### Desired Cooperation Partners

- OEM Manufacturing Partner
- Regional Distributor / Agent
- Maintenance Service Cooperation
- R&D and Technical Cooperation
- Others



## SUS・離型剤・治具製造

SUS Plates, Release Agents & Jig Manufacturing



- SUS プレート供給 SUS stainless steel sheet supply
- 専用離型剤 Exclusive Release Agent
- 真空ラミネーター・プレス機向け各種治具の設計・製造  
Design / Manufacture of vacuum laminators / Various fixtures for the press

400°C熱処理  
300°C高耐熱性  
Heat treatment at 400 °C  
Heat resistance up to 300 °C

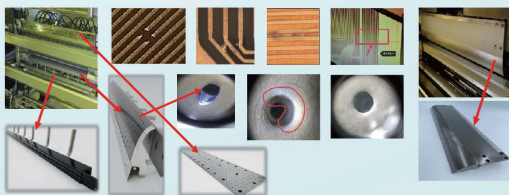


- Outside Plate 4140 H, 6150 H
- Cushion Pad
- Separator RHCS 40, RHCS 50
- Flow Stop Film
- Conformal Film
- Release Film (FPC PCB)

## 専用吸着治具

ABF Dry Film-Dedicated Suction Jig

- ABFドライフィルム貼り合わせ 備防止 Prevent scratches
- 搬送用専用吸着治具 ABF dry film lamination / Transport special fixture



## 真空ラミネーター部品製造

Vacuum Laminator & Pressing Machine Consumables

~400°C

工場 Factory

- 繰り返し500回〜使用可能 Reusable
- 温度、圧力均一 Temperature / Pressure uniformity

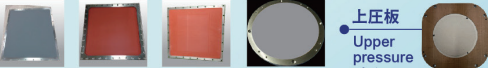
## クッション材

Cushioning material



## ダイヤフラム

Diaphragm



上圧板 Upper pressure plate

## ヒーター製造

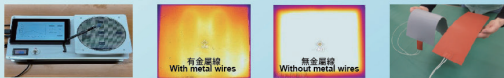
Heater

ボーイング社唯一指定日本メーカー  
The only designated manufacturer by Boeing airplane in Japan.

急速加熱2分で最大400°C 50%の電力節約!  
Heating to 400°C only 2 minutes!  
Save 50% electricity

工場 Factory  
Japan

- 超省エネ放射ヒーター開発 Ultra-energy-efficient thermal radiant heaters



- 低磁場、低電磁波 Low magnetic field / Low electromagnetic waves
- 工業用ヒーター、数字温度調節器、航空宇宙産業用ヒーター及び関連機器の製造  
Manufacture of industrial heaters / Digital temperature regulators  
Heaters for the aerospace industry / Related equipment manufacturing

## 異物除去用

~300°C

高温でも性能が落ちず、水洗いで繰り返し使えるクリーニングボード。  
High-temperature washable cleaning board

Product Specification Table

Type	Colors	Adhesive Types	Resin Thickness	Heat Resistance
AK	White / Black / Green / Blue	KSK / KMK / KHK / KH3K	60-300µm	Up to ~260°C
AL	Grey/Yellow	60°C Rubber Hardness	250µm	Up to ~220°C
AD	White	60°C Rubber Hardness	250µm	Up to ~320°C
Axe (Non-Silicon)	Black	AKS/AKM/AKH	50µm	Up to ~250°C

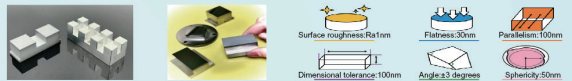


## ナノ研削技術/セラミック製品

Nano-Grinding Technology & Ceramic Products

Mirror-Polishing  
Nano-Polishing  
Blasting-Polishing  
DLC processing

- 超精密鏡面研削技術 Ultra-precision mirror grinding technology



- セラミック製品 Ceramic Products

医療業界向けセラミック部品 Medical industry

- セラミック材料により気孔密度を改善  
Ceramic materials improve pore density



- 半導体精密セラミック部品  
Semiconductor Precision Ceramic Components



## 過電流保護素子

Electric Protection Device

Acopa 華格科技股份有限公司  
ACPA TECHNOLOGY CO., LTD.

工場/台湾製  
Factory / MIT

- 電源ライン・電子機器の保護、サージ吸収  
Power supply protection, surge absorption, circuit safety protection



## 抵抗器材料

Resistor Materials

MaxOhms

工場/台湾製  
Factory / MIT

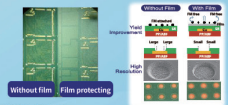
- 固定抵抗器 Fixed resistors
- 電力抵抗器 Power resistors



## ソルダーレジスト表面の保護・露光工用フィルム

Solder-Resist Protective Film (AJ)

- 露光気泡、異物(FM)、凹み、傷を改善  
Improve surface / Defects (FM) / Dents / Scratches
- 良好な剥離性、糊残りなし Easy to peel / No residue
- 酸化防止、色収差防止 Anti-oxidation / Anti-color aberration
- 高い光透過率と低い屈折率 High light transmittance / Low refractive index



## 電気メッキ処理/金属保護フィルム

Electroplating Engineering/Metal Protective Film

- 電気メッキ処理時の金属表面保護フィルム  
Metal surface protection film for electroplating
- 良好な剥離性、糊残りなし  
Easy to peel / No residue
- 輸送用保護フィルム、熱プレス工程にも対応  
Protective film for shipping / Heat pressing



- 高耐熱 High temperature resistance
- 耐薬性 Chemical resistance

## 熱剥離テープ/UVテープ/ BGテープ

Thermal Release Tape/UV Tape/BG Tape

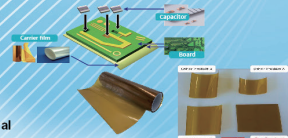
- Thermal Release Tape → 90°C-240°C、良好な剥離性、糊残りなし  
Easy to peel / No residue
- UV Tape → 90°C-200°C、UV照射後に粘着力低下、良好な剥離性、糊残りなし  
Easy to peel after UV exposure / No residue
- BG Tape → プロフェッショナルウェーハ研削テープ、優れた延性  
Professional wafer grinding tape / Excellent ductility



## QFN・DFN用高耐熱シート

High Heat-Resistant Film Products

- QFN・DFN用高耐熱シート QFN/DFN tape ■ 300°C  
耐高温PI素材 High-temperature resistant PI material  
良好な剥離性、糊残りなし Easy to peel / No residue  
パッケージングプロセスの歩留まり向上 Improve packaging process yield
- 耐高温フィルム High-temperature resistant film ■ 250°C-500°C  
高温ラミネート、保護、離型、電気絶縁用途など  
High-temperature bonding / Protection / Release / Electrical insulation



- 透明 ~250°C  
Transparent film
- 耐熱 ~500°C  
Heat resistant film

## Bba オープン炉用シート

Bba Oven-Cleaning Sheet

粉塵吸着性に優れたシート  
Sheet with excellent dust absorption properties

- ノンシリコン No siloxane volatilization
- オープン炉の異物洗浄 Oven-cleaning sheet for dust removal



Booth No. 3843

## Vesta Microsystem CO.,Ltd.

### 景晶科技股份有限公司



#### Company Address

3F., No. 17, Guangfu N. Rd., Hukou Township, Hsinchu County 303036, Taiwan (R.O.C.)

#### Website

Under construction

#### Registered Capital

NTD210M

#### Total Number of Employees

15

#### Main Products

iTGV (intelligent Through Glass Via) Product Solution & Lineup :

- SLIM TGV : body size, 15x15~40x40mm, layer count, 2~4L, TTL THK, <= 800um

- TGV : body size, 40x40~60x60mm, layer count, 4~8L, TTL THK, <= 1mm

- 2.5D Vitrum TGV : body size, 55~150mm, layer count, 6~10L, TTL THK, <= 1.2mm

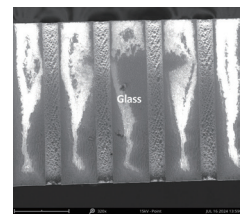
- TGV Interposer : body size, 60~150mm, layer count, 6~8L, TTL THK, <= 0.6mm

## Company Introduction

Vesta Microsystem CO., Ltd. is dedicated to developing & enabling IP-owned iTGV technology into semiconductor advanced packaging sector by high-accuracy & UPH LIDE (Laser Induced Deep Etching) hole, Direct-Cu microvia metallization (aspect ratio : ~10) & fine line RDLs and also committed to act as a partnered solution provider of semiconductor iTGV substrate.

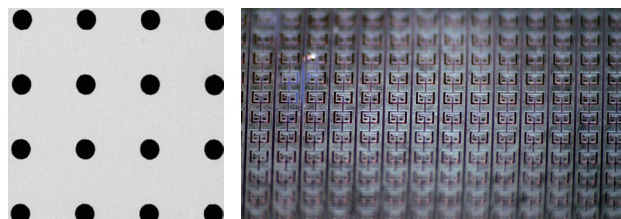
Why Vesta iTGV ?

- Leading LIDE Through Hole Formation (accu. +/- 2um ; > 80% straight hole)
- Quasi-Isotropic Conformal Coverage(iPVD) for High AR Hole (~10)
- Diversified Glass Materials Covering High-Low End Product Applications
- SeWaRe (glass cracking) Prevention
- Total Solution for Dense RDLs Built on iTGV Core



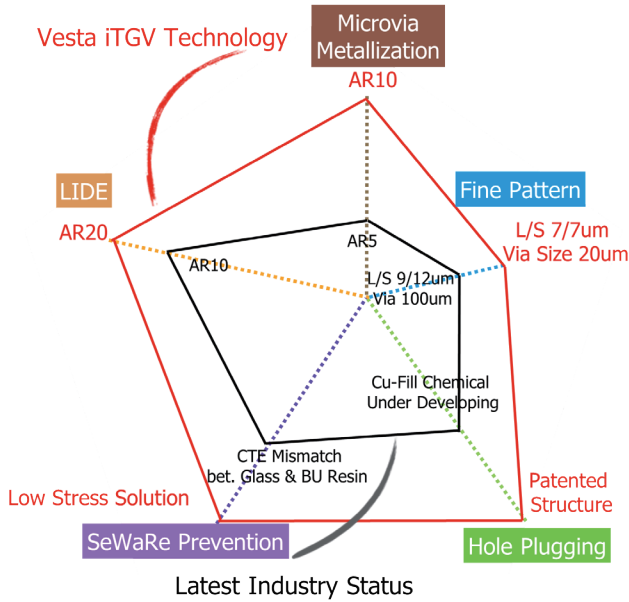
## Desired Cooperation Partners

- OEM Manufacturing Partner
- Regional Distributor / Agent
- Maintenance Service Cooperation
- R&D and Technical Cooperation
- Others

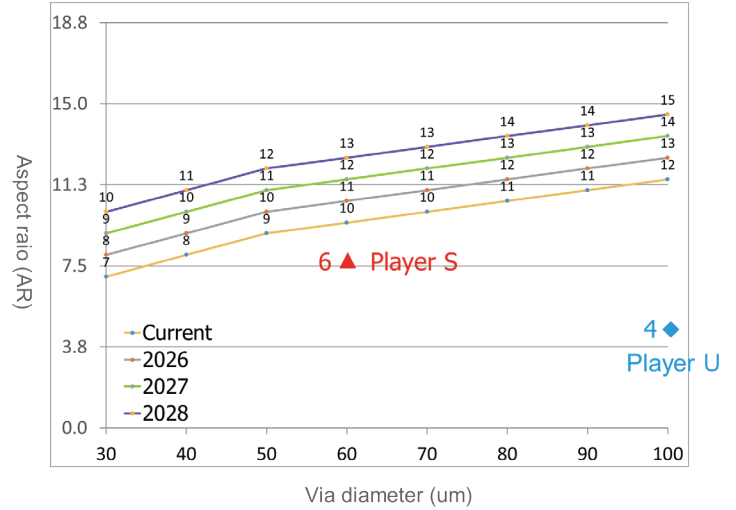


# Vesta iTGV Technology Briefing

(intelligent Through Glass Via)



Vesta TGV Roadmap (AR)



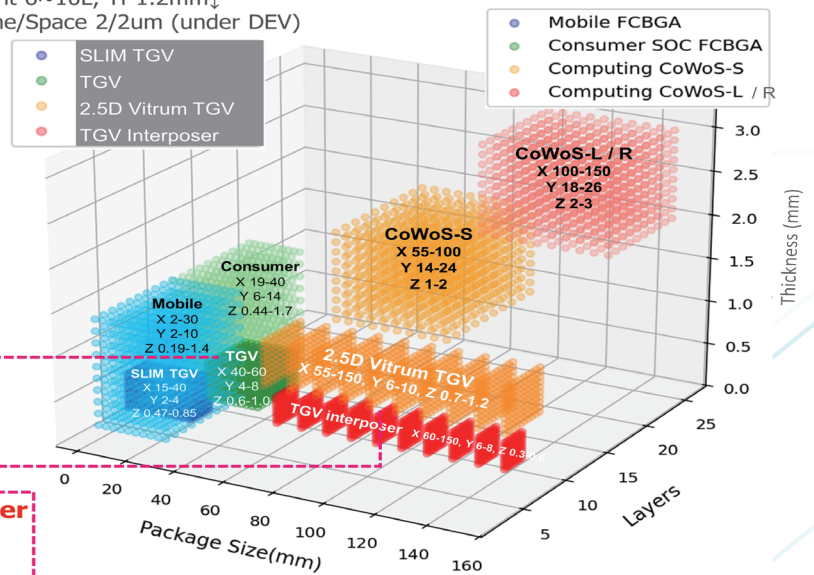
## Vesta iTGV Product Solution & Positioning

### iTGV Product Solution & Lineup

- **SLIM TGV** : Unit Size 15~40mm, Layer Count 2~4L, Tf 0.8mm↓
- **TGV** : Unit Size 40~60mm, Layer Count 4~8L, Tf 1.0mm↓
- **2.5D Vitrum TGV** : Unit Size 55~150mm, Layer Count 6~10L, Tf 1.2mm↓
- **TGV Interposer** : Unit Size 60~150mm, 6L RDLs, Line/Space 2/2um (under DEV)

**2D/2.1D Package**  
**SLIM TGV / TGV (2~8L)**  
 VS  
**ABF/BT-FCBGA (6~14L)**

**2.3D/2.5D Package**  
**2.5D Vitrum TGV (6~14L) / TGV Interposer**  
 VS  
**ABF-FCBGA (14~20L & TSV Interposer)**





Booth No. 3942

## Microcosm Technology Co., Ltd.

## 律勝科技股份有限公司

<b>Company Address</b>	No.8, Nanke 9th Rd., Shanhua Dist., Tainan City 741, Taiwan (R.O.C.)
<b>Website</b>	www.microcosm.com.tw/
<b>Registered Capital</b>	NTD 701,124,260
<b>Total Number of Employees</b>	100

### Main Products

1. Advanced Packaging & Semiconductor Applications: RDL Dielectric Materials- Photosensitive Polyimide (PSPI), Photosensitive Polybenzoxazole (PSPBO)
2. PCB / FPCB Manufacturing Materials SAP / m-SAP Build-up Materials, High-Frequency / High-Speed Dielectric Materials, Peelable Photosensitive Polyimide (Peelable PSPI), Flexible Copper Clad Laminate (FCCL), Bonding Sheets, Coverlay Materials
3. Display & Flexible Electronics: Transparent Polyimide (Transparent PI)

## Company Introduction

Microcosm Technology is a publicly listed advanced materials company based in Taiwan, with over two decades of experience in the development of functional polymer and polyimide-based materials.

Our core capabilities span process engineering, adhesive synthesis, photoresist synthesis, and polyimide synthesis. This integrated technical foundation enables us to develop application-driven material solutions optimized for process compatibility and reliable manufacturing.

We provide advanced materials for advanced packaging, FPCB/PCB, and high-density interconnect applications, including photosensitive polyimide (PSPI), photosensitive dielectric materials, build-up materials for SAP and m-SAP processes, and transparent polyimide materials.

Our strengths are defined by:

100% In-house R&D Excellence – All core technologies are developed internally, giving us full control over material formulation, structure design, and performance fundamentals.

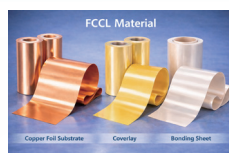
Global Patent Portfolio – More than 150 invention patents across the US, Taiwan, China, Japan, and Korea.

Strategic Integration Partner – We are more than just a supplier; we act as your technical ally, minimizing integration risks during New Product Introduction and enabling a seamless transition to high-volume manufacturing.

With centralized R&D, production, and technical support in Taiwan, and localized customer support in China, we work closely with customers on material evaluation, process validation, and development alignment to support scalable deployment.

## Desired Cooperation Partners

- OEM Manufacturing Partner
- Regional Distributor / Agent
- Maintenance Service Cooperation
- R&D and Technical Cooperation
- Others





20+ Years

Advanced polymer & PI material expertise

150+ Advanced Invention Patents

Covering materials, processes, and equipment integration

100+ PCB Manufacturers

Supporting customers across global PCB manufacturing markets

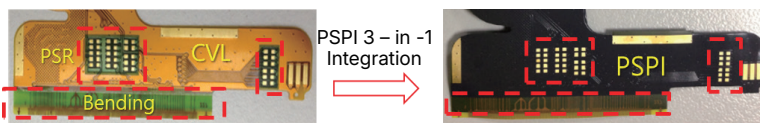


## Integrated Material Solutions for Advanced Manufacturing Processes From fine-line patterning to stable high-volume production

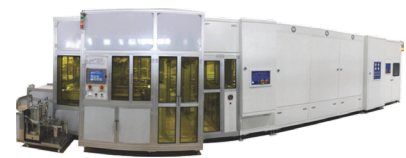
### Process Simplification for PCB & FPCB Manufacturing

#### Liquid PSPI Material

- Enables a single photosensitive material solution to replace conventional coverlay, PSR, and thermoset inks.
- Supports process simplification and thinner FPCB designs
- Compatible with dual-sided coating machines to integrate process steps and improve manufacturing efficiency



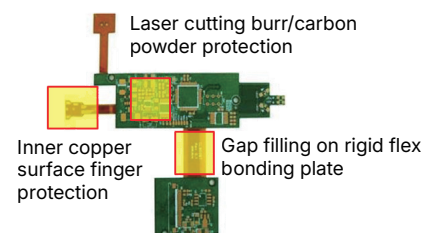
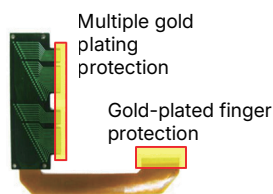
Conventional CVL Thinning	PSPI Thinning
EMI 10 $\mu$ m	EMI 10 $\mu$ m
5 $\mu$ m PI	12 $\mu$ m PSPI
12~15 $\mu$ m AD	1/3oz ED+Cu Plating
1/3oz ED + Cu Plating	1/2mil PI
Thinning 10~15%	1/3oz ED+Cu Plating
1/3oz ED + Cu Plating	12 $\mu$ m PSPI
12~15 $\mu$ m AD	EMI 10 $\mu$ m
5 $\mu$ m PI	



▲ Microcosm Patented Double-Sided Coating System

#### Peelable PSPI Material

- Temporary process protection materials designed to reduce manual handling and residual contamination risks.
- For blind vias, embedded cavities, and stepped PCB structures
- High heat resistance, alkaline removable, no residue

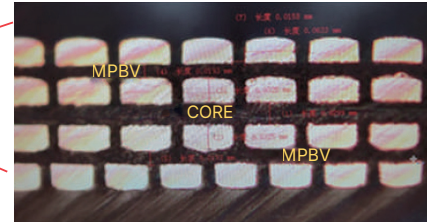
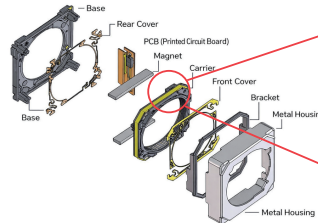


## Build-up Material Solutions

### MPBV – Microcosm Photosensitive Build-up Material

- Liquid-type, photosensitive
- Enables direct fine-resolution pattern formation via exposure and development.

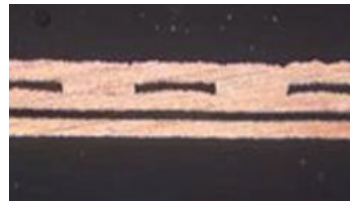
【 MPBV build-up application in FP coil of Voice Coil Motor 】



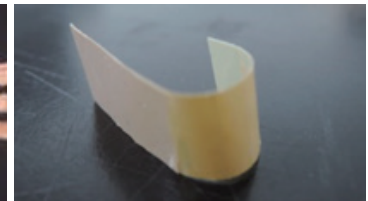
### FMBF – Flexible Microcosm Build-up Film

- Film-type, non-photosensitive
- Suitable for applications requiring both structural flexibility and electrical reliability

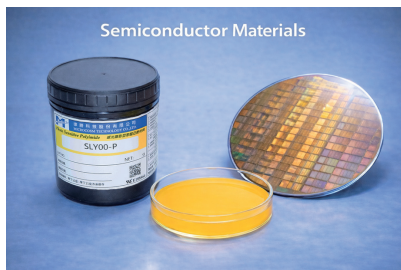
【 FMBF SAP build-up 】



【 FMBF bendable structure 】



## Fine-line Patterning & Dielectric Solutions



- Photosensitive dielectric and polyimide materials supporting RDL and high-density interconnect
- High-resolution via opening and fine-line definition with maintained process stability
- Applicable to advanced packaging and semiconductor-related applications

## Advanced Display & Flexible Device Materials



- Colorless Polyimide materials for flexible and foldable device applications.
- Designed for thin form factors with high bending endurance and structural stability.



# Gredmann

Booth No. 3944

## Gredmann Group 台灣格雷蒙股份有限公司

<b>Company Address</b>	11F, 170 Sec 3 Min Chuan E. Road, Taipei 105
<b>Website</b>	<a href="http://www.gredmann.com/">http://www.gredmann.com/</a>
<b>Registered Capital</b>	USD 98M
<b>Total Number of Employees</b>	600
<b>Main Products</b>	Materials and equipment for the electronics industry

### Company Introduction

A leading distributor of electronic materials and equipment with 47 years of experience, partnering with top-tier suppliers and serving customers across Greater China, Asia, the Americas, Europe, Africa, Brazil and beyond.

# Gredmann

PCB, IC substrate Material & Equipment

## About Gredmann

A leading distributor of electronic materials and equipment with 47 years of experience, partnering with top-tier suppliers and serving customers across Greater China, Asia, North America, South America, Europe and Middle East.



### Lamination Plates

*Separator Plates (SUS 630/420).*

- |                   |   |
|-------------------|---|
| 630 High Flatness | Ideal for high-layer-count and 5G high-frequency PCB applications |
| 420 High Hardness | Suitable for high-temperature processes                           |

*Top/Bottom Carrier Plates.*

- |            |   |
|------------|---|
| Hardox 450 | Premium wear-resistant steel known for its high hardness, toughness, and long service life. |
|------------|---|



### CCL/FCCL

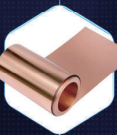
*CCL, FCCL, and Dummy board*

Our product portfolio covers 0.1-6mm thickness, with copper foil thickness ranging from 12-105um. Available in Customized Cut-Sheet sizes, as well as in Standard CCL Large Sheets and and PP Jumbo Roll.

### Cushion pads

*Green material – an excellent alternative to kraft paper and a solution for improving lamination bubbles – is highly favored by PCB, CCL manufacturers.*

Green Application in HDI PCB/CCL/IC substrate and High Temperature Hot Pressing. Cushion pad distribute pressure evenly and provide proper thermal cushioning so that heat can be transferred evenly to the material.



### Copper Foil

*Electronic Circuit Copper Foil, Thickness/um: 9 ~ 105*

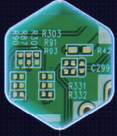
- ◆ Reverse Treated Copper Foil (RTF)
- ◆ High Temperature Elongation Copper Foil (HTE)
- ◆ Low Profile Copper Foil (LP)
- ◆ Low Profile Copper Foil – black roughening treatment (LP-B)



### Solder Mask

*High-performance Ink developed for both rigid and flexible PCBs, offering excellent reliability.*

1. **Solder mask ink** with green, white, blue and black color include UV types, Thermal curable types, traditional photomask and photomask-free exposure and development types.
2. **Legend (etch resist) ink** includes UV and thermally curable type for easy-to-use exposure-developing processes, available in screen printing, spraying, inkjet, and roller coating types.
3. **Marking inks** include UV and thermally curable types for screen printing and inkjet use.



### Dry Film

*Photosensitive material used to transfer circuit patterns onto PCBs.*

Dry film for IC substrate/HDI/PCB/FPC. Plenty experience and support customers all over the world.

- ◆ Inner/outer Layer
- ◆ Electroplating/ENIG



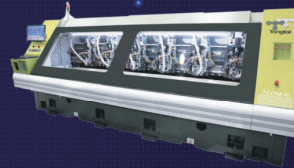
### Consumables

- ◆ Drill Bits, Routing Bits
- ◆ Copper Balls, Copper Oxide
- ◆ AL Sheet, Back-up Boards
- ◆ Filters/Filter Systems



### Drilling & Routing Machine

- ◆ Drill Bit Resharpening
- ◆ Auto Pinning and Taping System
- ◆ PCB drilling, routing machine
- ◆ Laser drilling, marking machine
- ◆ Drill Quality Analyze



### Wet Process System

*High-tech vertical plating system for Desmear, PTH, and Surface Treatment Processes.*

- ✓ Enhances productivity and factory safety
- ✓ Reduces environmental impact
- ✓ Developed by PROCESS ADVANCE TECHNOLOGY LTD., with decades of expertise and patented technologies
- ◆ **Electroless Ni/Pd/Au Plating Equipment**
  - Deposits Ni, Pd, Au on copper surface via chemical reaction
  - Flexible design options for PCB, HDI, UHDI, and IC Substrate plating.
- ◆ **Panel/Pattern Copper Plating Equipment**
  - Available with full automation (panel loading/unloading)
  - Supports MES, DMS, QMS integration



### High-Frequency Bonding Machine

- ◆ PIN-type High-Frequency Bonding Machine
- ◆ Semi-Automatic CCD Alignment Electromagnetic Heating Machine
- ◆ Customized CCD Alignment Electromagnetic Heating Machine



### Process Equipment

- ◆ Dry Film Lamination
- ◆ RTR Lamination
- ◆ ABF Vacuum Lamination
- ◆ ABF Mylar Peeler
- ◆ Plasma Desmear
- ◆ Conformal Coating System
- ◆ CNC PCB Prototyping machine



### Oven Systems

- ◆ Tunnel OVEN
- ◆ Box / N<sub>2</sub> Purge Oven
- ◆ UV and IR Ovens



Booth No. 3945

**TAI HONG CIRCUIT IND. CO., LTD.**  
**台豐印刷電路工業股份有限公司**

<b>Company Address</b>	No.81, Guangfu Rd., Fengshan village, Hukou township, Hsinchu county, Taiwan
<b>Website</b>	www.tci.com.tw
<b>Registered Capital</b>	USD34M
<b>Total Number of Employees</b>	1200
<b>Main Products</b>	Rigid PCB, substrate

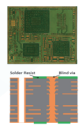
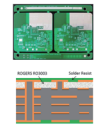
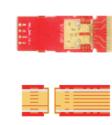
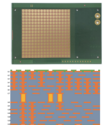
**Company Introduction**

Established in 1969, TCI is the oldest professional printed circuit board manufacturing company in Taiwan. It has been deeply cultivating Taiwan and fulfilling its social responsibilities. As a part of the automotive supply chain, with the rapid development of electric vehicles around the world, we continue to upgrade process equipment and increase production capacity, thereby enhancing Taiwan's industrial competitiveness.

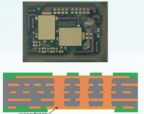
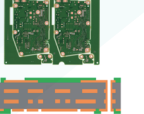
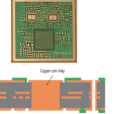
**Desired Cooperation Partners**

- OEM Manufacturing Partner
- Regional Distributor / Agent
- Maintenance Service Cooperation
- R&D and Technical Cooperation
- Others


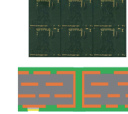
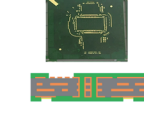
**High Speed & Low Loss Products**

	<b>HDI for V2X</b>	<b>Hybrid IVH for Telematics</b>	<b>Transceiver</b>	<b>HDI for Phased Array Antenna</b>
				
<b>Product Features</b>	<ul style="list-style-type: none"> <li>• Small unit with high line density</li> <li>• Better electrical and signal transportation by short route and improving EMI/RFI/ESD</li> </ul>	<ul style="list-style-type: none"> <li>• Low loss dielectric (Df 0.005) for the high frequency demand. (up to 77 GHz.)</li> <li>• Hybrid dielectric stacks provide diverse product features.</li> </ul>	<ul style="list-style-type: none"> <li>• Low Dk, low Df hybrid material for high speed &amp; low loss demand</li> </ul>	<ul style="list-style-type: none"> <li>• Low Dk, low Df material.</li> <li>• Better electrical and signal characteristics meet the stringent requirements of phased arrays in aerospace and military radar</li> </ul>
<b>Product Application</b>	Smart Phone, Tablet, Wearable devices, vehicle, storage device, V2X	Automotive radar, GPS, mobile, wireless patch antennas, satellite reception, storage device, Honeycomb car network	Transceiver	Frequency Modulated Radar satellite reception, WiFi, 5G

**High Power & Thermal Solution**

	<b>Coreless + thermal bar substrate (5L)</b>	<b>Heavy Copper PCB</b>	<b>Cu coin inlay PCB</b>
			
<b>Product Features</b>	<ul style="list-style-type: none"> <li>• Thin and asymmetric structure combined with mSAP stabilizes signal transportability.</li> <li>• Thermal bar design improves heat dissipation to stabilize the PA output.</li> </ul>	<ul style="list-style-type: none"> <li>• Support products with excessive current, elevated temperatures and recurring thermal cycling in computer, automotive, military, and industrial controls.</li> <li>• Heavy Cu layer up to 6 oz.</li> </ul>	<ul style="list-style-type: none"> <li>• Cu coin inlay in cavity of PCB.</li> <li>• Customized Cu coin dimension.</li> <li>• High reliable permanent hole plugging.</li> <li>• Alternative solution of thermal vias and thermal bars are available.</li> </ul>
<b>Product Application</b>	Mobile phones, Tablets, Bluetooth, RFID readers, Satellite communications, 5G base stations, Antenna couplers	Power supplies and power converters, Automotive industry, Overload and protection Relays, Solar panel inverters.	High heat dissipation product such as LED lighting fixtures, 5G communications, bases, server.

**High Reliability Package Substrate**

	<b>PBGA substrate (HDI)</b>	<b>CSP substrate (4L)</b>	<b>mSAP substrate</b>
			
<b>Product Features</b>	<ul style="list-style-type: none"> <li>• Finger Pitch/Top/Gap → 80/40/20</li> <li>• Trace Pitch/Line/Space → 70/25/25</li> <li>• Total Thickness → 560µm</li> </ul>	<ul style="list-style-type: none"> <li>• Finger Pitch/Top/Gap → 80/40/20</li> <li>• Trace Pitch/Line/Space → 60/20/20</li> <li>• Total Thickness → 180µm</li> </ul>	<ul style="list-style-type: none"> <li>• High-density wiring design.</li> <li>• Fine line 1/5=20/20µm</li> </ul>
<b>Product Application</b>	Video games, LCD TV, SSD, WI FI AP, Set Top Box	LCD Cluster, Smart Mirror, USB	Mobile phones, Tablets, and HDI communication products

# The Leading PCB Pioneer in Taiwan

**TCI** 台豐印刷電路  
工業股份有限公司  
TAI HONG CIRCUIT IND. Co., Ltd.

*Advanced PCB & Substrate Manufacturer Since 1969*

**CCP** 長春集團  
Chang Chun Group  
長春人造樹脂廠股份有限公司  
Chang Chun Plastics, Taiwan

**MGC**  
三菱ガス化学  
Mitsubishi Gas Chemical, Japan

- One of Taiwan's largest producers in the plastics and petrochemical industries since 1949.
- Products for PCB & substrate : Copper foil & CCL 、 epoxy resins 、 molding compound 、 electronic grade chemicals.
- The first Japan company to develop the PWB's base material.
- Products for PCB & substrate : BT resin (inventor) 、 BT laminates 、 epoxy laminates 、 electronic grade chemicals.

## The 1<sup>st</sup> certificated Automotive PCB supplier in Taiwan since 1989

Examples of Application : Automotive、Semiconductor、ICT、Server、Aerospace、Medical Equipment

Production capacity : PCB : 95,000m<sup>2</sup> per month ; IC Substrate (BGA) : 18,000m<sup>2</sup>

Certificates : ISO9001、14001、45001、13485、IATF16949

**TCI**

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E-mail : Fuming.Yang@tci.com.tw



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Taiwan Printed Circuit Association (TPCA)

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